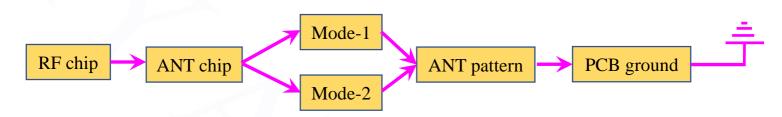


#### P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09

#### ✓ Features:

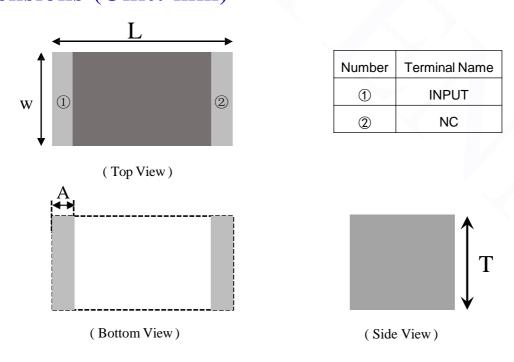
- 1. Surface mounted element with a small dimension of  $1.6 \times 0.8 \times 0.8$  mm meet future miniaturization trend.
- 2. Embedded and LTCC (low temperature co-fired ceramic) technology is able to integrate with system design as well as beatifying the housing of final product.
- 3. Miniaturization, wideband, high stability, low ESR, and low tolerance.
- 4. Dual-band resonances in the dominant and harmonic modes enables multiband operations.
- 5. Novel ground-radiation technique enables radiation from both the antenna and the ground plane.



## **Applications:**

- 1. Bluetooth
- 2. Dual-band WLAN
- 3. ISM and UWB

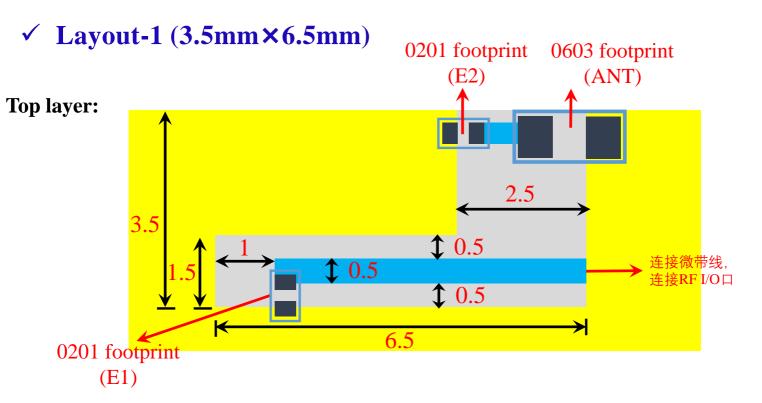
# ✓ Dimensions (Unit: mm)

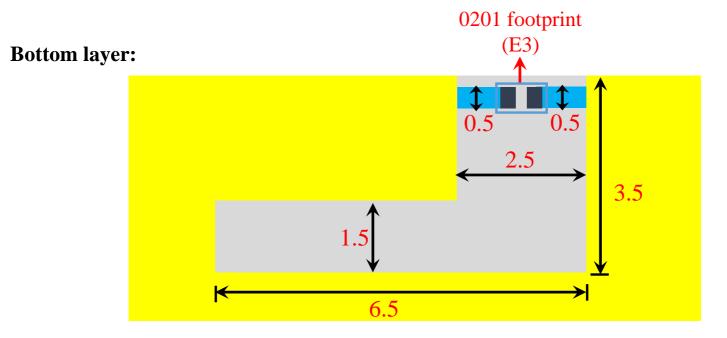


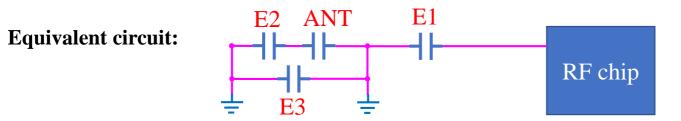
Symbols	L	W	Т	A
Dimensions	$1.60\pm0.20$	$0.80 \pm 0.20$	$0.80 \pm 0.20$	$0.30 \pm 0.10$



#### P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09

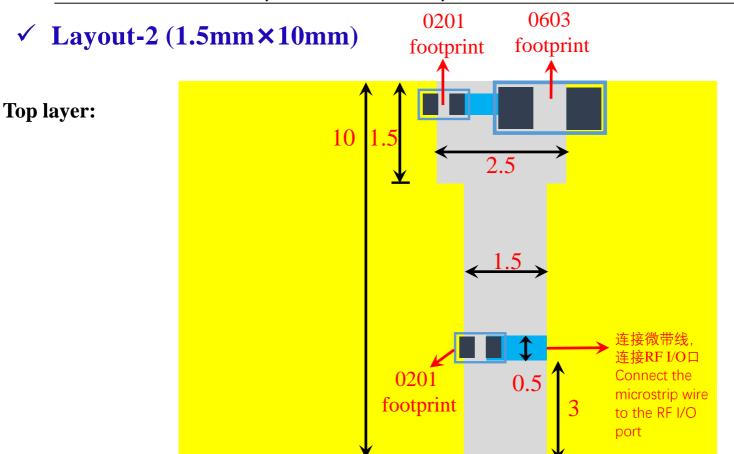




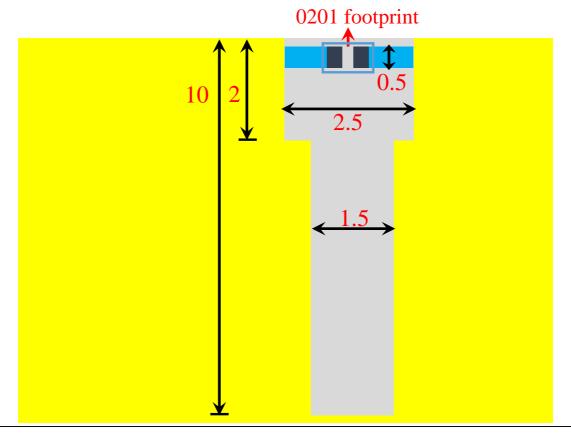




#### P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09



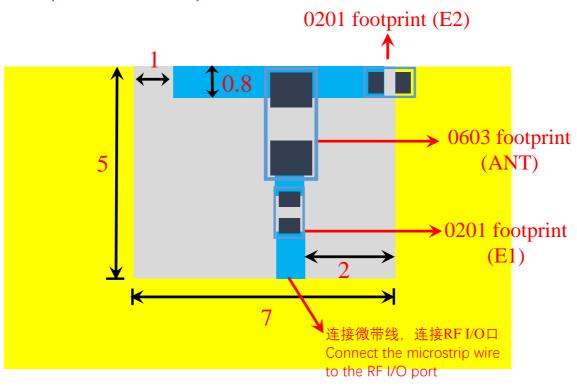
**Bottom layer:** 



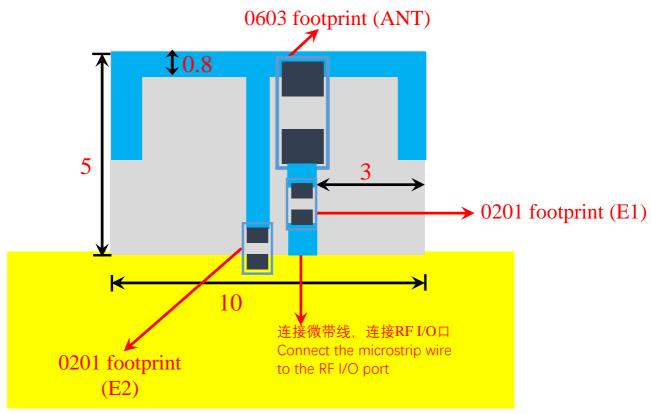


#### P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09

# $\checkmark$ Layout-3 (5mm×7mm)



# $\checkmark$ Layout-4 (5mm×10mm)



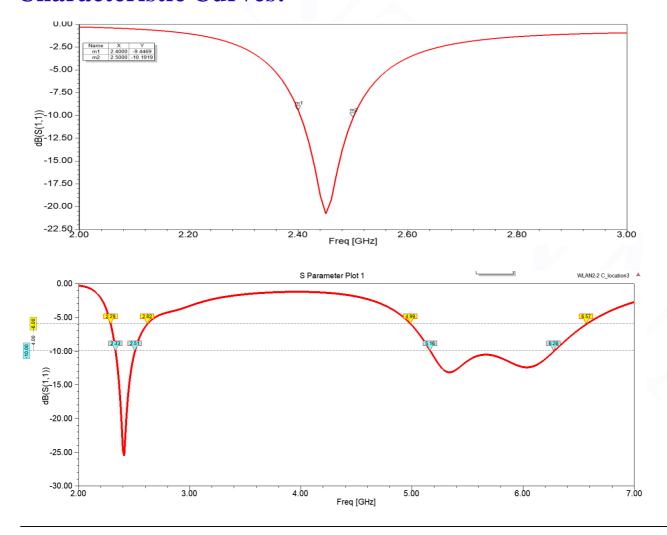


#### P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09

## ✓ Electrical Characteristics:

	Feature	Specification		
1	Central frequency	2.4GHz&5.5GHz		
2	Bandwidth	>150MHz		
3	Peak gain	>3dBi		
4	VSWR	<2		
5	Antenna type	SMD		
6	Azimuth beamwidth	Omnidirectional		
7	Impedance	$50\Omega$		

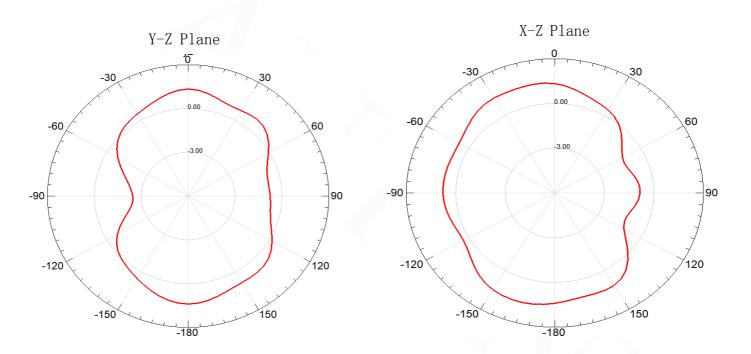
# **✓** Characteristic Curves:



## P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09

#### ✓ Radiation Pattern:





# **✓ Radiation Performance:**

Frequency	2450MHz	5500MHz
Avg. gain	-0.85	-1.30
Peak gain	3.0	3.5
Efficiency	82%	78%

#### 深圳市宝安区前进二路宝运达物流信息大厦12A10/12A11

 12A10/12A11, Baoyunda Logistics Information Building, Qianjin Second Road, Baoan District, Shenzhen

### P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09

## ✓ Dependability Test

Test Temperature  $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Operating Temperature  $-25^{\circ}\text{C} \sim +125^{\circ}\text{C}$ Temperature  $5\sim 40^{\circ}\text{C}$ Relative Humidity  $20\sim 70\%$ 

#### ✓ Moisture Proof

Temperature:  $40\pm2^{\circ}$ C Humidity:  $90\sim95\%$ RH

Duration: 500h

Recovery conditions: Room temperature Recovery Time: 24h (Class1) or 48h (Class2)

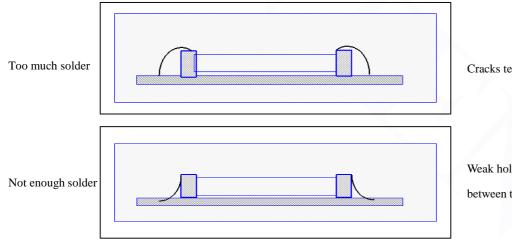
#### ✓ Solderability

At least 95% of the terminal electrode is covered by new solder.

Preheating conditions:80 to  $120^{\circ}$ C;  $10\sim30$ s.

Solder Temperature: 235 ± 5°C Duration: 2 ±0.5s, Solder Temperature: 245 ± 5°C Duration: 2 ±0.5s

# ✓ Optimum Solder Amount for Reflow Soldering

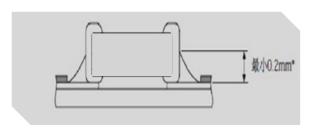


Cracks tend to occur due to large stress.

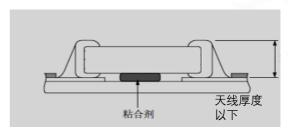
Weak holding force may cause bad connection between the chip and PCB.

# **✓** Recommended Soldering Amounts

The optimal solder fillet amounts for re-flow soldering



The optimal solder fillet amounts for wave soldering



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 12A10/12A11, Baoyunda Logistics Information Building, Qianjin Second Road, Baoan District, Shenzhen

#### P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09

## ✓ Temperature Cycle Test

 $10\pm1$ S Applied Force: 5N Duration:  $10\pm1$ S Preheating conditions: up-category temperature, 1h

Recovery time: 24±1h Initial Measurement

Cycling Times: 5 times, 1 cycle, 4 steps:

# ✓ Resistance to Soldering Heat

Preheating 80 to 120°C; 10~30s.SolderTemperature: 235±5°C; Duration: 2±0.5s; SolderTemperature: 245±5°C

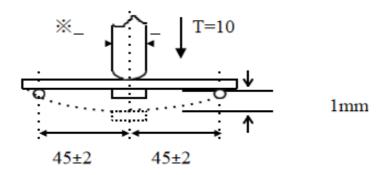
Duration:  $2\pm0.5$ s; Preheating 100 to  $200^{\circ}$ C;  $10\pm2$ min. Solder Temperature:  $265\pm5^{\circ}$ C; Duration:  $10\pm1$ s

Clean the capacitor with solvent and examine it with a 10X(min.) microscope.

Recovery Time: 24±2h

Recovery condition: Room temperature

#### **✓** Resistance to Flexure of Substrate



Test Board: Al<sub>2</sub>O<sub>3</sub> or PCB Warp: 1mm Speed: 0.5mm/sec.

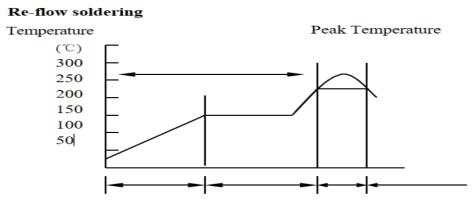
Unit: mm

The measurement should be made with the board in the bending position.



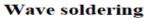
#### P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09

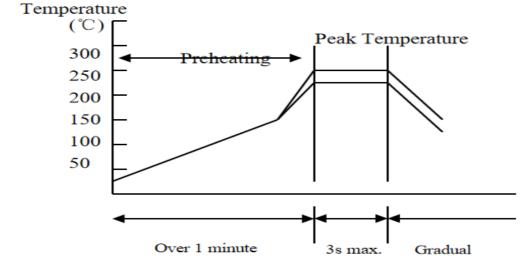
#### The temperature profile for soldering



	Pb-Sn 焊接	无铅焊接		
	Pb-Sn soldering	Lead-free soldering		
尖峰温度	230℃~250℃	240℃∼260℃		
Peak temperature	230 C ~ 230 C	240 C ~ 200 C		

While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as:  $T \le 150$  °C.



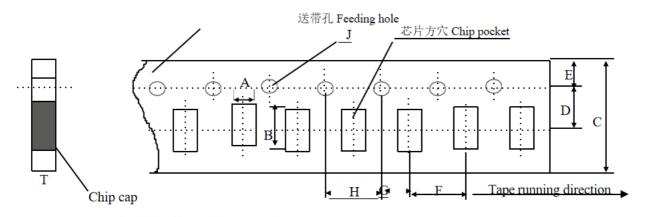


	Pb-Sn 焊接	无铅焊接		
	Pb-Sn soldering	Lead-free soldering		
尖峰温度	230℃~260℃	240℃~270℃		
Peak temperature	250 C 200 C	240 8 270 8		



#### P/N: HY160808 SRF07, HY160808 SRF08, HY160808 SRF09

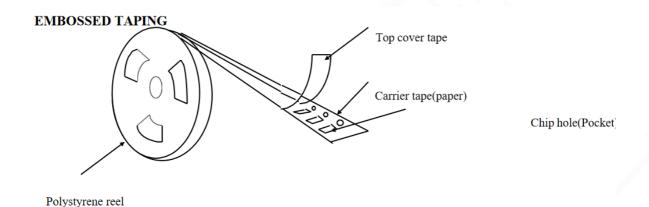
# Dimensions of paper taping



Unit: mm

代号Code 纸带规格 papersize	A	В	С	D*	E	F	G*	Н	J	T
D.†	1.10	1.90	8.00	3.50	1.75	4.00	2.00	4.00	1.50	1.10
尺寸 	±0.10	±0.10	±0.10	±0.05	±0.10	±0.10	±0.10	±0.10	-0/+0.10	Max

Reel (4000 pcs/Reel)



# ✓ Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition). Temperature:  $5\sim40^{\circ}$ C /Relative Humidity:  $20\sim70\%$